

- a second bump disposed on the first metal bar; and
a reference bump disposed on the second metal bar, wherein the second bump is adjacent to the first bump,
wherein the first metal bar and the second metal bar are positioned such that an angle between a line from the reference bump to the first bump and a line from the reference bump to the second bump has a value substantially equal to 150 degrees.
- 11 (Twice Amended) A patterned bump array for a power grid of an integrated circuit, comprising:
a reference bump disposed on a first metal bar;
a first bump disposed on a second metal bar; and
a second bump disposed on a second metal bar,
wherein the second bump is adjacent to the first bump, and
wherein the first bump, the second bump, and the reference bump are arranged such that an angle between a line from the reference bump to the first bump and a line from the reference bump to the second bump has a value substantially equal to 150 degrees.
- 17 (Twice Amended) A bump layout for a power grid of an integrated circuit, comprising:
a reference bump disposed on a first metal bar;
a first bump disposed on a second metal bar; and
a second bump disposed on a second metal bar,
wherein the second bump is adjacent to the first bump, and
wherein the first metal bar and the second metal bar are arranged such that an angle between a line from the reference bump to the first bump and a line from the reference bump to the second bump has a value substantially equal to 150 degrees.